

DC1230.doc	REVISION			
	REV.	DESCRIPTION	DATE	APPVD.
	1	Procedures for manufacturers of bare PC Boards	04/30/09	RD
	2	Added a requirement	05/28/09	RD
	3	Changed format	06/01/09	FA
4	Added solder sample requirement	10-1-09	FRA	

1.0 SCOPE

The following are the rules for vendors manufacturing bare Printed Circuits Boards for Sunburst Electronics

	APPROVALS:		SUNBURST ELECTRONICS INC. 420 EAST BAYFRONT PARKWAY ERIE, PA 16507-1456		
	PREP.	DATE			
	ENG. RD	04/30/09	TITLE	RULES FOR VENDORS MANUFACTURING PCB'S	
	PURCHASING. KB	04/24/09	SIZE A	DWG. NO. DC1230	REV. NO. 2
	Q.C.	04/27/09	SCALE	RELEASE DATE 04/30/09	SHEET 1 OF 3

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2.0 The following requirements at a minimum apply to all bare Printed Circuit Boards that are manufactured for Sunburst Electronics.

3.0 Violation of these rules may result in rejection of material:

3.1 *Authority of Documents* - When a conflict arises between this specification, the detail drawings and/or the purchase order, the following order of precedence shall apply:

- a. Purchase Order
- b. Detail drawing
- c. This specification
- d. Other applicable documents.

3.2 *Minimum Workmanship Requirements* - If no other workmanship standard is required then the boards shall be built to IPC-A-600, Class II, current revision.

3.3 *UL Recognition* - The vendor must be UL recognized to fabricate boards to a minimum UL category of 94V0. Vendor identification as defined in UL796, must be placed on the solder side of the board, or as specified on individual bare board drawings. Where there is no space to put the UL identification on the board, the vendor ID may be put on the pallet, or silk-screened on the top of the board.

3.4 *Required Files Submitted* - The files used to manufacture the board will consist of some or all of the following:

- a. Gerber files.
- b. Fabrication drawing.
- c. Panel drawing.
- d. .readme file.

3.5 *Testing* – Boards with 2 or more layers must be final tested 100% for shorts and opens.

3.6 *Packaging and Shipping* – Boards must be sealed for moisture protection.

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3.7 *Documentation* – The vendor should provide the following documentation.

- a. Final paste files that show the panelization and location of fiducials should be sent prior to the first shipment.
- b. A Certificate of Conformance is required with each shipment.
- c. First Article Inspection results should be sent with the first delivery, and after each revision change.
- d. When the vendor changes a major process, or changes facilities, notification must be sent to Sunburst Electronics.

3.8 *Solder Sample*

- a. When an order shipped for the first time a solder sample board is required; after first order it will be required only when requested.
- b. If process is changed significantly then a solder sample is required.

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